**Project Design Document**

From MI Phone CEO

To CEO of Indchip,

Dear Bhavna,

My name is Xing Chao Chan, I am the CEO of MI Phone

I am releasing my next Phone in month of December. For this phone, I am looking for a RISC-V based implementation, with 12kB of on-chip SRAM

Power and area are not an issue, as my team has come up with a new technology to reduce on-chip switching and leakage power, but my concern is performance

Now, we are providing you the synthesized netlist and a specification file in below link

<https://github.com/kunalg123/icc2_workshop_collaterals/blob/master/raven_wrapper.synth.v>

<https://github.com/kunalg123/icc2_workshop_collaterals/blob/master/raven_wrapper.sdc>

I have heard your company has been doing a fabulous job in the performance market, and we would like to sign an MoU with your company, so we can start our collaboration work very soon.

You can decide your foundry which you would need to achieve the frequency and send an invoice for the same (including 20% overhead charges). We will process the payment soon to Indchip account, for you to get started

Really happy to collaborate with you and your team, and looking forward to work with you for all upcoming phones from MI

Regards

Xing Chao Chan